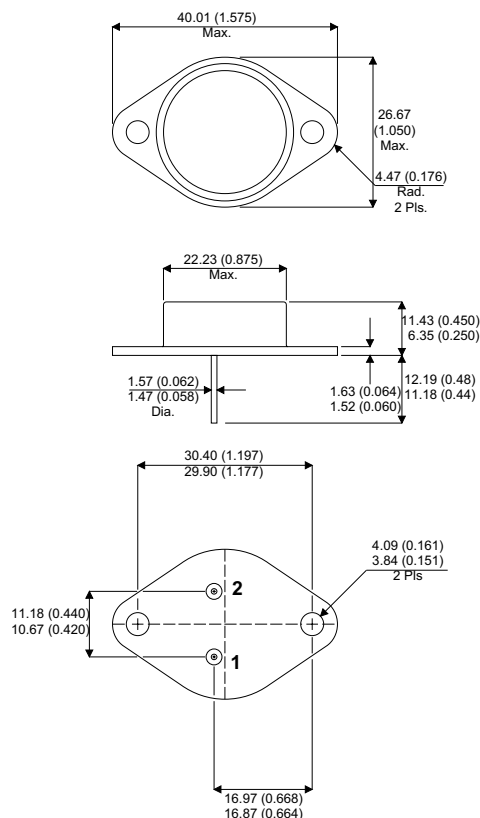


MECHANICAL DATA

Dimensions in mm (inches)


TO-3 Metal Package

Pin 1 – Gate

Pin 2 – Source

Case – Drain

P-CHANNEL MOSFET IN A TO3 FOR HIGH RELIABILITY APPLICATIONS.
 V_{DSS} **100V**
 I_D **40A**
 $R_{DS(on)}$ **0.07Ω**
FEATURES

- FAST SWITCHING
- SCREENING OPTIONS AVAILABLE


ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

V_{GS}	Gate – Source Voltage	$\pm 20V$
I_D	Continuous Drain Current ($T_{case} = 25^{\circ}C$)	40A
I_D	Continuous Drain Current ($T_{case} = 100^{\circ}C$)	29A
I_{DM}	Pulsed Drain Current ¹	140A
P_D	Power Dissipation	200W
	Linear Derating Factor	1.3W/ $^{\circ}C$
E_{AS}	Single Pulse Avalanche Energy ²	780mJ
E_{AR}	Repetitive Avalanche Energy ¹	21mJ
T_J, T_{stg}	Operating Junction and Storage Temperature Range	-55 to $+150^{\circ}C$
$R_{\theta JC}$	Junction – Case Thermal Resistance	0.75 $^{\circ}C/W$
$R_{\theta JA}$	Junction – Ambient Thermal Resistance	62 $^{\circ}C/W$

Notes

- 1) Repetitive rating; pulse width limited by max. junction temperature.
- 2) $V_{DD} = -25V$, $L = 3.5mH$, $R_G = 25\Omega$, $I_{AS} = -21A$, Starting $T_J = 25^{\circ}C$

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^{\circ}\text{C}$ unless otherwise stated)

Parameter		Test Conditions		Min.	Typ.	Max.	Unit
STATIC ELECTRICAL RATINGS							
V _{(BR)DSS}	Drain – Source Breakdown Voltage	V _{GS} = 0V	I _D = –250μA	–100			V
R _{DS(on)}	Static Drain to Source On Resistance ⁴	V _{GS} = –10V	I _D = –24A			0.07	Ω
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS}	I _D = –250μA	– 2.0		–4.0	V
g _{fs}	Forward Transconductance	V _{DS} = –8V	I _D = –20A	14			S
I _{DSS}	Drain to Source Leakage Current	V _{DS} = 100V	V _{GS} = 0V			–25	μA
		V _{DS} = 100V	V _{GS} = 0V T _J = 125°C			–250	
I _{GSS}	Gate to Source Forward Leakage	V _{GS} = 20V				100	nA
I _{GSS}	Gate to Source Reverse Leakage	V _{GS} = -20V				–100	
DYNAMIC CHARACTERISTICS							
C _{iss}	Input Capacitance	V _{GS} = 0V			2700		pF
C _{oss}	Output Capacitance	V _{DS} = –25V			790		
C _{rss}	Reverse Transfer Capacitance	f = 1MHz			450		
Q _g	Total Gate Charge ⁴	I _D = –21A				180	nC
Q _{gs}	Gate – Source Charge ⁴	V _{DS} = –80V V _{GS} = –10V				25	
Q _{gd}	Gate – Drain (“Miller”) Charge ⁴					97	
t _{d(on)}	Turn–On Delay Time ⁴	V _{DD} = –50V			17		ns
t _r	Rise Time ⁴	I _D = –21A			86		
t _{d(off)}	Turn–Off Delay Time ⁴	R _G = 2.5Ω			79		
t _f	Fall Time ⁴	R _G = 2.4Ω			81		
SOURCE – DRAIN CHARACTERISTICS							
I _S	Continuous Source Current	MOSFET symbol showing the integral reverse p-n junction 				–40	A
I _{SM}	Pulse Source Current ¹					–140	
V _{SD}	Diode Forward Voltage ⁴	T _J = 25°C, I _S = 21A, V _{GS} = 0V				–1.6	V
t _{rr}	Reverse Recovery Time ⁴	d _i / d _t ≤ –100A/μs			170	260	ns
Q _{rr}	Reverse Recovery Charge ⁴	T _J = 25°C, I _F = -21A			1.2	1.8	μC
t _{on}	Forward Turn–On Time	negligible					—
PACKAGE CHARACTERISTICS							
L _D	Internal Drain	Between lead, 6mm(0.25in.) from package and center of die contact				4.5	nH
L _S	Internal Source Inductance					7.5	

Notes

- 1) Repetitive rating; pulse width limited by max. junction temperature.
- 2) $V_{DD} = -25V$, $L = 3.5\text{mH}$, $R_G = 25\Omega$, $I_{AS} = -21A$, Starting $T_J = 25^{\circ}\text{C}$
- 3) $I_{SD} \leq -6.5A$, $di/dt \leq -100A/\mu s$, $V_{DD} \leq BV_{DSS}$, $T_J \leq 150^{\circ}\text{C}$, Suggested $R_G = 7.5\Omega$
- 4) Pulse Test: Pulse Width $\leq 300\text{ms}$, $\delta \leq 2\%$